NEC

MOS FIELD EFFECT TRANSISTOR
2SJ626

P-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

DESCRIPTION

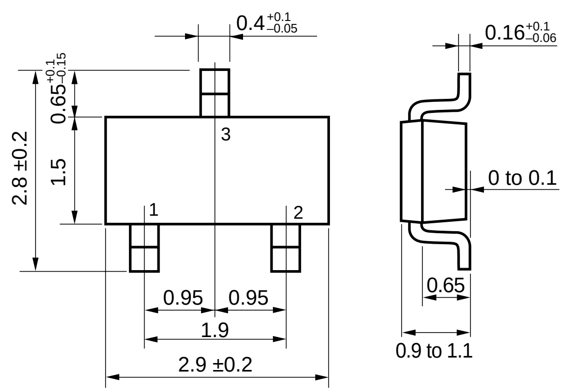
The 2SJ626 is a switching device which can be driven directly by a 4.0 V power source.

The 2SJ626 features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

FEATURES

- 4.0 V drive available
- Low on-state resistance
  - $R_{DS(on)1}$ = 388 mΩ MAX. (V_{GS} = –10 V, I_D = –1.0 A)
  - $R_{DS(on)2}$ = 514 mΩ MAX. (V_{GS} = –4.5 V, I_D = –1.0 A)
  - $R_{DS(on)3}$ = 556 mΩ MAX. (V_{GS} = –4.0 V, I_D = –1.0 A)

PACKAGE DRAWING (Unit: mm)



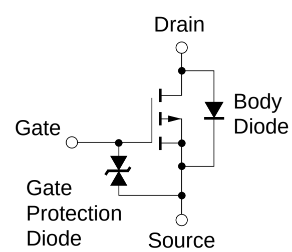
1 : Gate
2 : Source
3 : Drain

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SJ626	SC-96 (Mini Mold Thin Type)

Marking: XN

EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	–60	V
Gate to Source Voltage (V_{DS} = 0 V)	V_{GSS}	∓20	V
Drain Current (DC) (T_A = 25°C)	$I_{D(DC)}$	∓1.5	A
Drain Current (pulse) Note1	$I_{D(pulse)}$	∓6.0	A
Total Power Dissipation	P_{T1}	0.2	W
Total Power Dissipation Note2	P_{T2}	1.25	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	–55 to +150	°C

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1%

2. Mounted on FR-4 board, t ≤ 5 sec.

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

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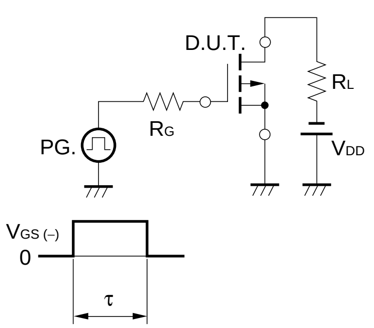
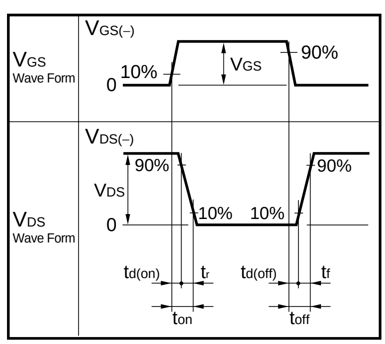
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = –60 V, V_{GS} = 0 V			–1.0	μA
Gate Leakage Current	I_{GSS}	V_{GS} = ∓20 V, V_{DS} = 0 V			∓10	μA
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = –10 V, I_D = –1.0 mA	–1.5	–2.1	–2.5	V
Forward Transfer Admittance	$\| y_{fs} \|$	V_{DS} = –10 V, I_D = –1.0 A	1.0	2.5		S
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = –10 V, I_D = –1.0 A		310	388	mΩ
	$R_{DS(on)2}$	V_{GS} = –4.5 V, I_D = –1.0 A		385	514	mΩ
	$R_{DS(on)3}$	V_{GS} = –4.0 V, I_D = –1.0 A		417	556	mΩ
Input Capacitance	C_{iss}	V_{DS} = –10 V		255		pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		45		pF
Reverse Transfer Capacitance	C_{rss}	f = 1.0 MHz		17		pF
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = –30 V, I_D = –1.0 A		17		ns
Rise Time	t_r	V_{GS} = –10 V		29		ns
Turn-off Delay Time	$t_{d(off)}$	R_G = 10 Ω		92		ns
Fall Time	t_f			65		ns
Total Gate Charge	Q_G	V_{DD} = –48 V		8.2		nC
Gate to Source Charge	Q_{GS}	V_{GS} = –10 V		1.3		nC
Gate to Drain Charge	Q_{GD}	I_D = –1.5 A		2.2		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 1.5 A, V_{GS} = 0 V		0.86		V

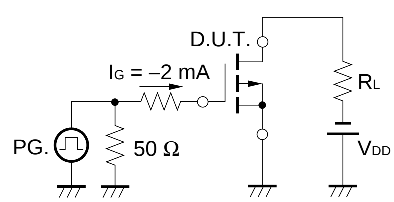
TEST CIRCUIT 1 SWITCHING TIME





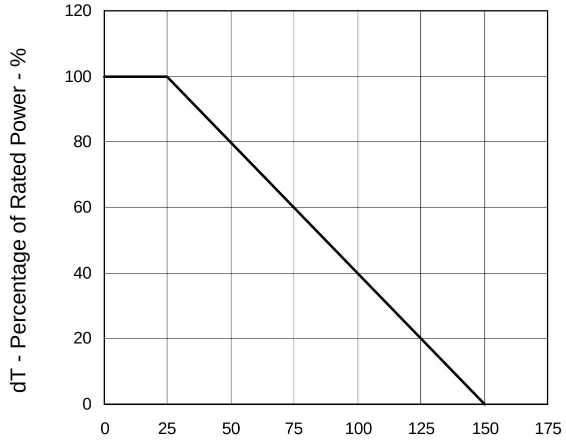
τ = 1 μs
Duty Cycle ≤ 1%

TEST CIRCUIT 2 GATE CHARGE



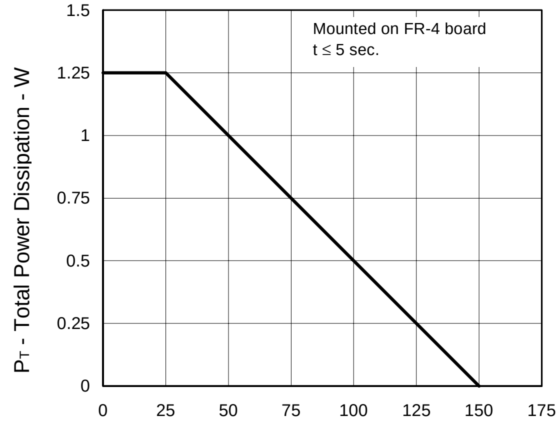
TYPICAL CHARACTERISTICS (T_A = 25°C)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



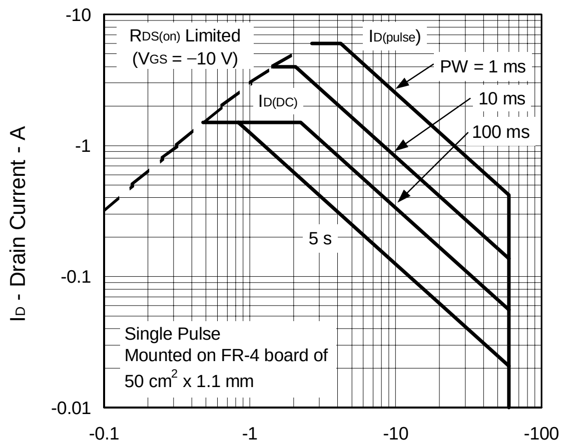
TA - Ambient Temperature - °C

TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



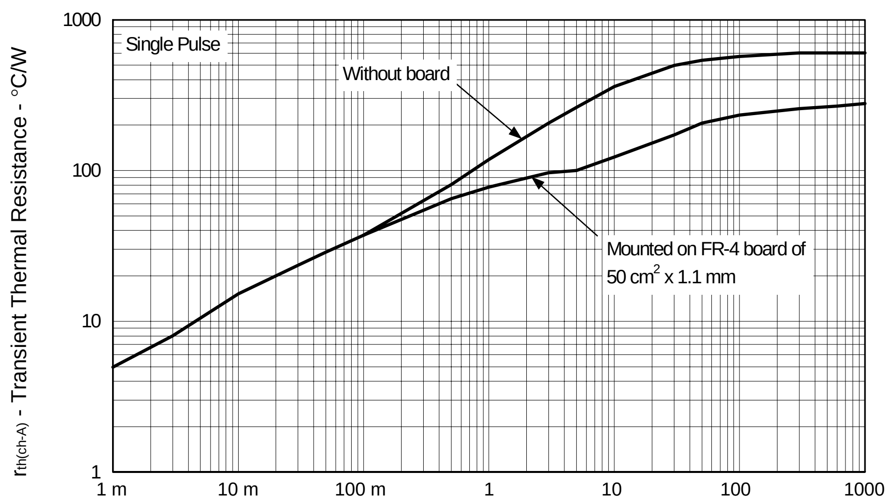
TA - Ambient Temperature - °C

FORWARD BIAS SAFE OPERATING AREA



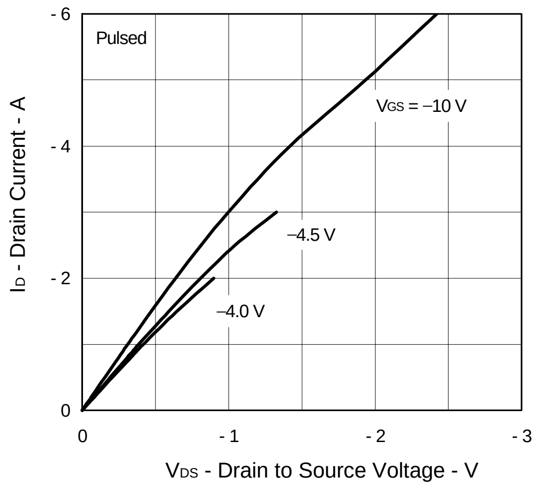
VDS - Drain to Source Voltage - V

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

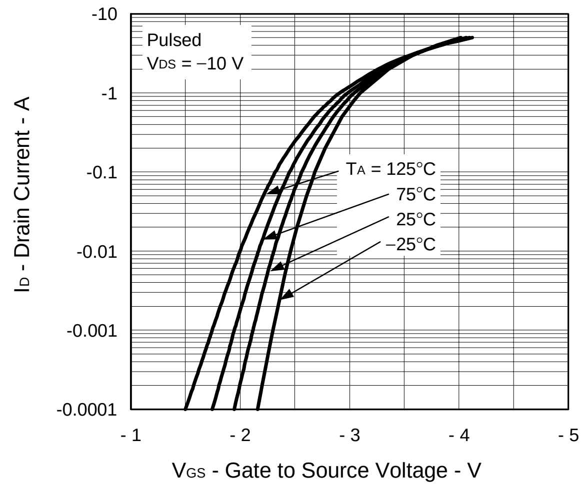


PW - Pulse Width - s

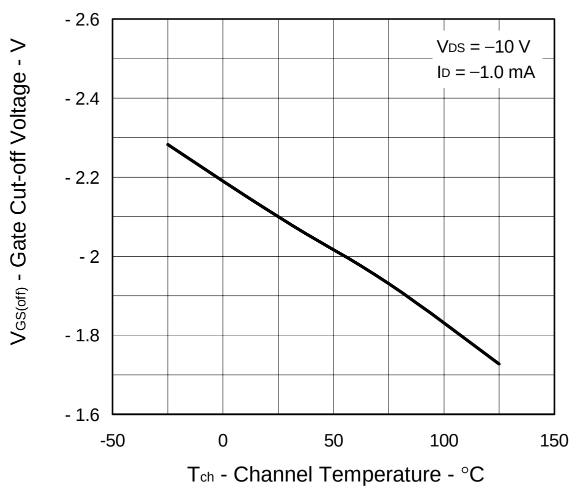
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



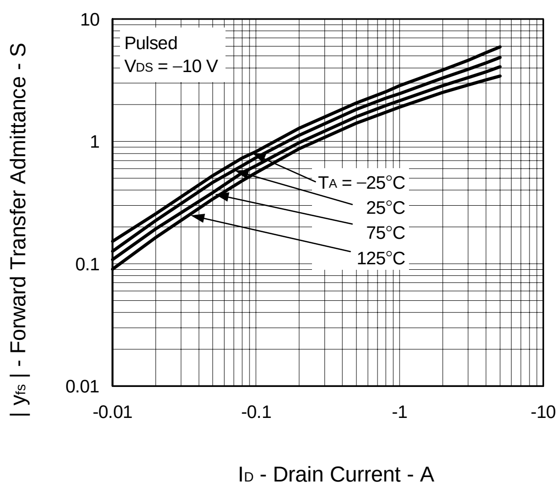
FORWARD TRANSFER CHARACTERISTICS



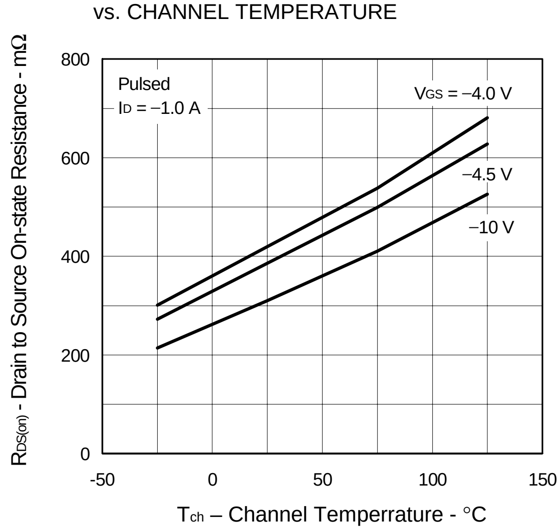
GATE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE



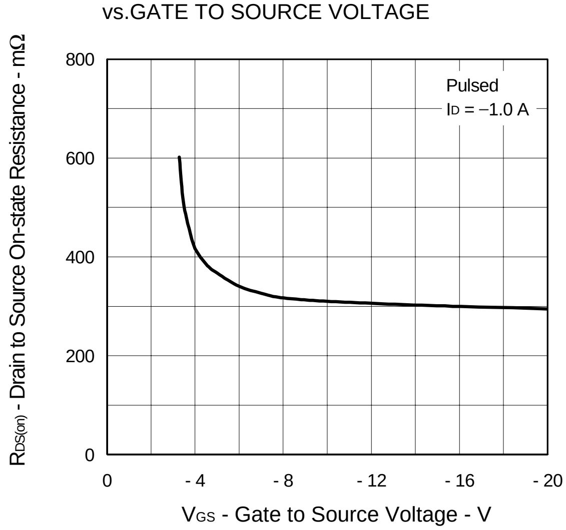
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



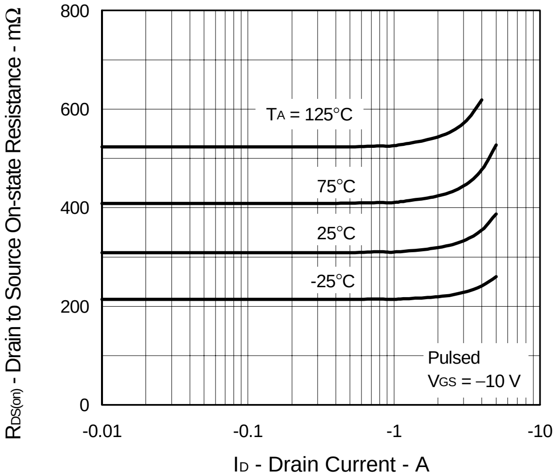
DRAIN TO SOURCE ON-STATE RESISTANCE
vs. CHANNEL TEMPERATURE



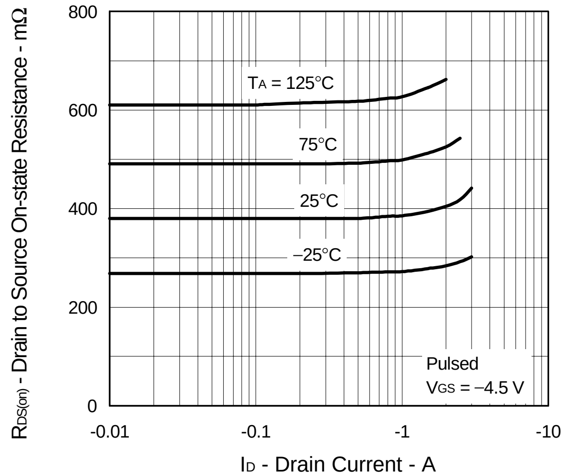
DRAIN TO SOURCE ON-STATE RESISTANCE
vs.GATE TO SOURCE VOLTAGE



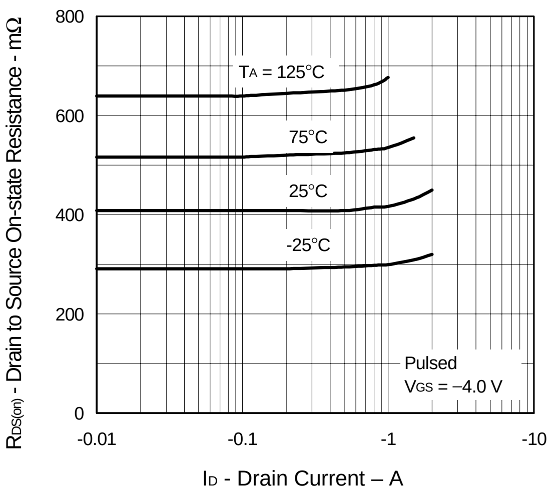
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



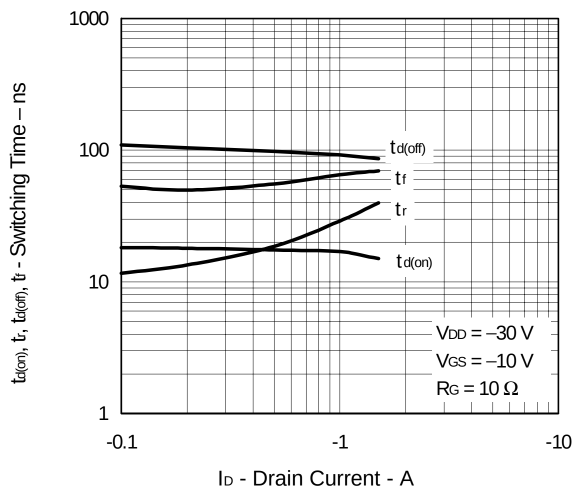
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



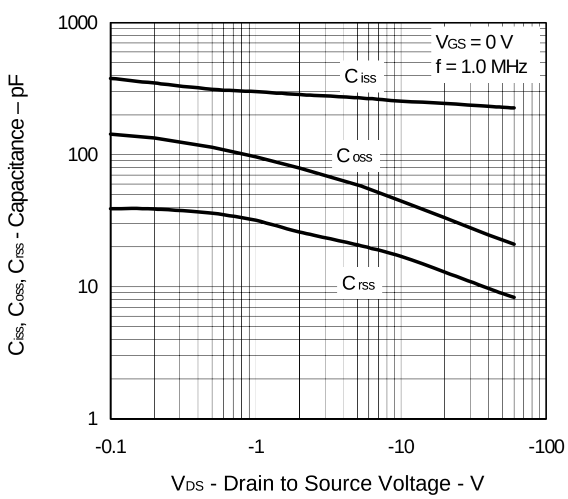
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



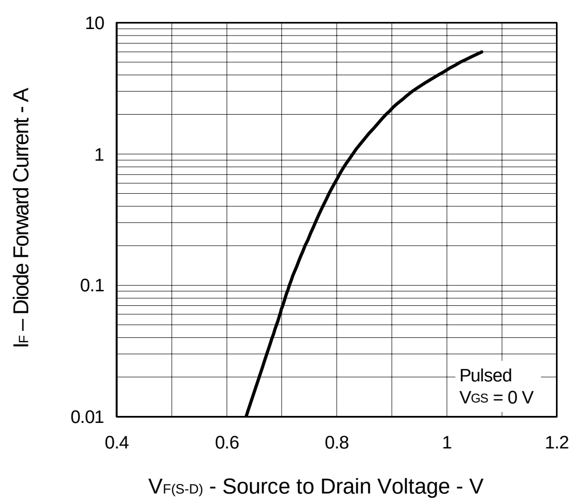
SWITCHING CHARACTERISTICS



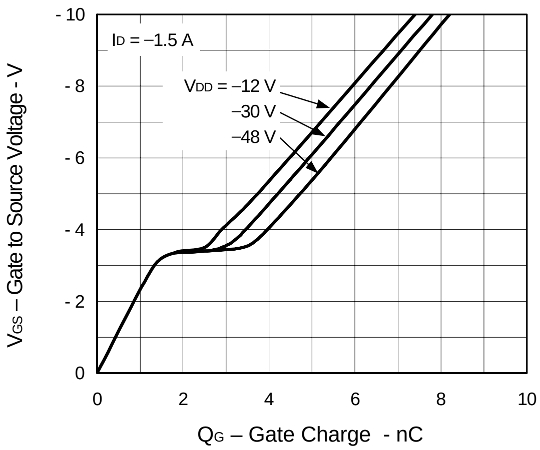
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



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